

PATENT APPLICATION SERIAL NO. _____

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE
FEE RECORD SHEET

07/29/2002 EFSPROD 00000006 10064575

01 FC:101	740.00 OP
02 FC:581	40.00 OP

JC474 U.S. PTO
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Stylesheet Version: 1.0

Patent fees are subject to annual revisions on or about October 1st of each year.

TOTAL FEES AUTHORIZED: \$ 780

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Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

Subtotal For Basic Filing Fee: \$ 740

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 13	103	\$ 18	0	\$ 0
Independent Claims: 2	102	\$ 84	0	\$ 0

Subtotal For Extra Claims Fees: \$ 0

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40

TRANSMITTAL FORM



Electronic Version 1.0.3

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Attorney Docket
Number:7808-US-
PASubmission Type: Utility Patent
Filing

BUMP LAYOUT ON SILICON CHIP

First Named Inventor: Mr. Wen-Chih Yang

SUBMITTED BY

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Attached Files:

declaration	7808declaration1.tif
declaration	7808declaration2.tif
specification	7808usf.xml
patent-assignments	7808usasgn.xml
fee-transmittal	7808usfee.xml

Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 16725
Application ID: 10064575
Title of Invention: BUMP LAYOUT ON SILICON CHIP
First Named Inventor: Wen-Chih Yang
Domestic/Foreign Application: Domestic Application
Filing Date: null
Effective Receipt Date: 2002-07-29
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Filing Type: new-utility
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Government, c=US
Certificate Message Digest: VrHnsD2Mu/gBdRXY1QWxAA==
Total Fees Authorized: \$780.0
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Attached Image File(s):

7808declaration1.tif

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Comments: